## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

: Examiner: S.J. Cohen
Hans-Jurgen Albrecht, et al. )
: Group Art No.: 1793

Application No.: 10/554,274 )

: Confirmation No.: 3094

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For: SOLDERING MATERIAL BASED ON Sn )
Ag AND Cu : July 1, 2011

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## AMENDMENT

Sir:

In response to the Office Action mailed February 1, 2011, the due date for which having been extended for a period of time of two (2) months up to and through July 1, 2011 by the accompanying Petition Under 37 C.F.R. § 1.136(a) and fee, kindly amend the subject application as follows:

Amendment to the claims begins on page 2 of this paper.

Remarks begin on page 3 of this paper.